



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSP742T	Issued	01. April 2021
MA#	MA001427674		
Package	PG-DSO-8-24	Weight*	83.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.250	1.50	1.50	15045	15045
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.717	0.86		8634	
	non noble metal	copper	7440-50-8	29.121	35.06	35.97	350564	359738
wire	noble metal	gold	7440-57-5	0.373	0.45	0.45	4491	4491
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1193	
	plastics	epoxy resin	-	4.560	5.49		54898	
	inorganic material	silicondioxide	60676-86-0	44.910	54.07	59.68	540628	596719
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9797	9797
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7828	7828
glue	plastics	epoxy resin	-	0.093	0.11		1117	
	noble metal	silver	7440-22-4	0.437	0.53	0.64	5265	6382
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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